LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1790AIS6-4.096#TRMPBF		(Engineering Calculation)		TSOT-23		
(printed on: 7/16/2011 12:56:24 PM)					TOTAL MASS (g):	0.01254276
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000567	1000000	45205.38
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.004582	975000	365310.5
		Iron (Fe)	7439-89-6	0.000113	24000	9009.185
		Phosporus (P)	7723-14-0	1.00E-06	300	79.72729
		Zinc (Zn)	7440-66-6	3.00E-06	700	239.1819
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0	0	0
		Lead Frame Total:		0.004699	1000000	374638.6
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.000643756	1000000	51324.92
		External Plating Total:		0.000643756	1000000	51324.92
		Inter. Plating Ni	7440-02-0	0	0	0
		Inter. Plating Ag	7440-22-4	8.00E-05	1000000	6378.183
		Internal Plating Total:		8.00E-05	1000000	6378.183
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000409	750000	32608.46
		Tin (Sn)	7440-31-5	0	0	0
		Lead (Pb)	7439-92-1	0	0	0
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Antimony (Sb)	7440-36-0	0	0	0
		Resin (EP)		0.000136	250000	10842.91
		Die Attach Total:		0.000545	1000000	43451.38
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000345	58000	27505.92
		Bromine (Br)	40039-93-8	0	0	0
		Silica (SiO2)	60676-86-0	0.005287	890000	421518.2
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0
		Metal Hydroxid		0.000297	50000	23679.01
		Carbon Black (C)	1333-86-4	1.20E-05	2000	956.7275
		Encapsulation Total:		0.005941	1000000	473659.8
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	6.70E-05	1000000	5341.729
				TOTAL MASS (g):		0.01254276